

ALUMINUM-COPPER CLAD

FOR HEATSINKS



If materials that fulfill more than one property are required for efficient thermal management, clad materials are used.

Advantages:

- > High thermal conductivity
- > High electrical conductivity
- > Excellent soldering properties
- > Sinterability
- > Surface coating properties
- > No contact resistance between Copper and Aluminum
- Highly malleable, easy to fabricate
- > Impact extrusion possible
- > Weight and cost advantage compared to pure Copper

Chip connnection

Chip

Printed circuit board

Heat sin

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- > Clad Materials > Bimetals > Nickel Strips > Metal Foils
- > Photochemical Etching > Sheet Metal Working > Waterjet Cutting
- > Electroforming > Parylene Coating > Materials Engineering etc.

